Lecture 17: Hardware Specialization and Algorithm Specific Programming

Parallel Computing Stanford CS149, Fall 2023

Energy-constrained computing

Energy (Power x Time)-constrained computing

- Supercomputers are energy constrained
 - Due to shear scale of machine
 - Overall cost to operate (power for machine and for cooling)
- Datacenters are energy constrained
 - Reduce cost of cooling
 - Reduce physical space requirements
- Mobile devices are energy constrained
 - Limited battery life
 - Heat dissipation

Performance and Power



Pursuing highly efficient processing... (specializing hardware beyond just parallel CPUs and GPUs)

Why is a "general-purpose processor" so inefficient?

Wait... this entire class we've been talking about making efficient use out of multi-core CPUs and GPUs... and now you're telling me these platforms are "inefficient"?

Consider the complexity of executing an instruction on a modern processor...

Read instructionAddress translation, communicate with icache, access icache, etc.Decode instructionTranslate op to uops, access uop cache, etc.Check for dependencies/pipeline hazardsIdentify available execution resourceUse decoded operands to control register file SRAM (retrieve data)Move data from register file to selected execution resourcePerform arithmetic operationMove data from execution resource to register fileUse decoded operands to control write to register file SRAM



H.264 video encoding: fraction of energy consumed by functional units is small (even when using SIMD)



Fast Fourier transform (FFT): throughput and energy benefits of specialization



Digital signal processors (DSPs)

Programmable processors, but simpler instruction stream control paths

Complex instructions (e.g., SIMD/VLIW): perform many operations per instruction (amortize cost of control)



[Developed by DE Shaw Research]

Anton supercomputer for molecular dynamics

- Simulates time evolution of proteins
- ASIC for computing particle-particle interactions (512 of them in machine)
- Throughput-oriented subsystem for efficient fast-fourier transforms
- Custom, low-latency communication

network designed for communication patterns of N-body simulations





Specialized processors for evaluating deep networks

Countless recent papers at top computer architecture research conferences on the topic of ASICs or accelerators for deep learning or evaluating deep networks...

- Cambricon: an instruction set architecture for neural networks, Liu et al. ISCA 2016
- EIE: Efficient Inference Engine on Compressed Deep Neural Network, Han et al. ISCA 2016
 Cnvlutin: Ineffectual-Neuron-Free Deep Neural Network Computing, Albericio et al. ISCA 2016
- Minerva: Enabling Low-Power, Highly-Accurate Deep Neural Network Accelerators, Reagen et al. ISCA 2016
- vDNN: Virtualized Deep Neural Networks for Scalable, Memory-Efficient Neural Network Design, Rhu et al. MICRO 2016
- Fused-Layer CNN Architectures, Alwani et al. MICRO 2016
- Eyeriss: A Spatial Architecture for Energy-Efficient Dataflow for Convolutional Neural Network Chen et al. ISCA 2016
- PRIME: A Novel Processing-in-memory Architecture for Neural Network Computation in ReRAMbased Main Memory, Chi et al. ISCA 2016
- DNNWEAVER: From High-Level Deep Network Models to FPGA Acceleration, Sharma et al. MICRO 2016



Intel Lake Crest ML accelerator (formerly Nervana) Lake Crest

FPGAs (Field Programmable Gate Arrays)

- Middle ground between an ASIC and a processor
- FPGA chip provides array of logic blocks, connected by interconnect
- Programmer-defined logic implemented directly by FGPA



Image credit: Bai et al. 2014

THH

Specifying combinatorial logic as a LUT

- Example: 6-input, 1 output LUT in Xilinx Virtex-7 FPGAs
 - Think of a LUT6 as a 64 element table



40-input AND constructed by chaining outputs of eight LUT6's (delay = 3)



Image credit: [Zia 2013]

Modern FPGAs



- A lot of area devoted to hard gates
 - Memory blocks (SRAM)
 - DSP blocks (multiplier)

Amazon EC2 F1

FPGA's are now available on Amazon cloud services



What's Inside the F1 FPGA?



System Logic Block: Each FPGA in F1 provides over 2M of these logic blocks

DSP (Math) Block: Each FPGA in F1 has more than 5000 of these blocks

I/O Blocks: Used to communicate externally, for example to DDR-4, PCIe, or ring

Block RAM: Each FPGA in F1 has over 60Mb of internal Block RAM, and over 230Mb of embedded UltraRAM

amazon webservices Webinars

Efficiency benefits of compute specialization

- Rules of thumb: compared to high-quality C code on CPU...
- Throughput-maximized processor architectures: e.g., GPU cores
 - Approximately 10x improvement in perf / watt
 - Assuming code maps well to wide data-parallel execution and is compute bound
- Fixed-function ASIC ("application-specific integrated circuit")
 - Can approach 100-1000x or greater improvement in perf/watt
 - Assuming code is compute bound and is not floating-point math

Choosing the right tool for the job



Mapping Algorithms to Execution Resources



General Purpose Processor

Dual-core processor, multi-threaded cores (4 threads/core). Two-way superscalar cores: each core can run up to two independent instructions per clock from <u>any of its threads</u>, provided one is scalar and the other is vector



Memory (DRAM) **Custom Memory 0** (SRAM) Custom Registers Custom V0 V4 V5 Control V1 **V2** V6 V3 V7 ALU (16-wide vector ALU) **Custom Memory 1** (SRAM)

Special Purpose Processor (Accelerator)

So You Want to Design an Accelerator for Your Algorithm

- Traditionally, you must spend years becoming an expert in VHDL or Verilog, Chisel...
- High-Level Synthesis (HLS): Vivado HLS, Intel OpenCL, and Xilinx SDAccel
 - Restricted C with pragmas
 - These tools sacrifice performance and are difficult to use
- Spatial is a high-level language for designing hardware accelerators that was designed to enable performance-oriented programmers to specify
 - Parallelism: specialized compute
 - Locality: specialized memories and data movement

Spatial-lang.org

HOME PUBLICATIONS TUTORIALS DOC FORUM DOWNLOAD	Q
SPATIAL	
A high-level language for programming accelerators	
GET STARTED VIEW SOURCE	

Spatial: DSL for Accelerator Design

- Simplify configurable accelerator design
 - Constructs to express:
 - Parallel patterns as parallel and pipelined datapaths
 - Independent parallelism
 - Dependent parallelism
 - hierarchical control
 - explicit memory hierarchies
 - Explicit parameters
 - All parameters exposed to the compiler
 - Simple APIs to manage CPU ↔ Accelerator communication
- Allows programmers to focus on "interesting stuff"
 - Designed for performance-oriented programmers (parallelism and locality)
 - More intuitive than CUDA: dataflow instead of threads

The Spatial Language: Memory Templates

Explicit memory hierarchy Typed storage templates	<pre>val buffer = SRAM[UInt8](C) val image = DRAM[UInt8](H,W)</pre>
Registers	<pre>val accum = Reg[Double] val fifo = FIFO[Float](D) val lbuf = LineBuffer[Int](R,C) val pixels = ShiftReg[UInt8](R,C)</pre>
Explicit transfers across memory hierarchy Dense and sparse access	buffer load image(i, j::j+C) buffer gather image(a, 10)
Streaming abstractions	<pre>val videoIn = StreamIn[RGB] val videoOut = StreamOut[RGB]</pre>

The Spatial Language: Control Templates

Blocking/non-blocking interaction with CPU

Accel { ... } Accel(*) { ... }

Arbitrary state machine / loop nesting with implicit control signals

```
FSM[Int]{s => s != DONE }{
    case STATE0 =>
        Foreach(C by 1){j => ... }
        case STATE1 => ...
        Reduce(0)(C by 1){i => ... }
}{s => nextState(s) }
```

The Spatial Language: Design Parameters

Spatial templates capture a variety of design parameters:

```
val P = 16 (1 \rightarrow 32)
Explicit parallelization factors
                                                Reduce(0)(N by 1 par P){i =>
                                                  data(i)
                                                \{(a,b) => a + b\}
                                                Stream.Foreach(0 until N){i =>
Implicit/Explicit control schemes
                                                  •••
                                                }
                                                val B = 64 (64 \rightarrow 1024)
                                                val buffer = SRAM[Float](B)
Explicit size parameters for stride
                                                Foreach(N by B){i =>
and buffer sizes
                                                }
                                                Foreach(64 par 16){i =>
 Implicit memory banking and buffering
                                                  buffer(i) // Parallel read
schemes for parallelized access
                                                }
```

Inner Product



Let's build an accelerator to see how Spatial works

Sketch of generated hardware

Inner Product in C

```
// Set up accumulator and memory pointers
int output = 0;
int* vec1 = (int*)malloc(N * sizeof(int));
int* vec2 = (int*)malloc(N * sizeof(int));
// Iterate through data and accumulate
for (int i = 0; i < N; i++) {</pre>
  output = output + (vec1(i) * vec2(i));
}
```

Here is inner product written in C for a CPU





Inner product in Spatial allows the programmer to build a hardware accelerator

- Start of code looks like C example
- Accel instantiates "for" loop in hardware









 Spatial generates multi-step controllers (This Reduce controller's final step will handle the accumulation)



```
// Set up host and memory pointers
val output = ArgOut[Int]
val vec1 = DRAM[Int](N)
val vec2 = DRAM[Int](N)
// Create accelerator
Accel {
    // Allocate on-chip memories
    val tile1 = SRAM[Int](tileSize)
    val tile2 = SRAM[Int](tileSize)
    // Specify outer loop
    Reduce(output)(N by tileSize){ t =>
        // Prefetch data
        tile1 load vec1(t :: t + tileSize)
        tile2 load vec2(t :: t + tileSize)
```

- Spatial generates multi-step controllers
- Spatial manages communication with DRAM



}{a, b => a + b}

- // Set up host and memory pointers val output = ArgOut[Int] val vec1 = DRAM[Int](N) val vec2 = DRAM[Int](N) // Create accelerator // Allocate on-chip memories val tile1 = SRAM[Int](tileSize) val tile2 = SRAM[Int](tileSize) // Specify outer loop Reduce(output)(N by tileSize){ t => // Prefetch data tile1 load vec1(t :: t + tileSize) tile2 load vec2(t :: t + tileSize) // Multiply-accumulate data val accum = Reg[Int](0) Reduce(accum)(tileSize by 1 par i){ i => tile1(i) * +i1e2(i) }{a, b => a + b} $\{a, b => a + b\}$
- Spatial generates multi-step controllers
- Spatial manages communication with DRAM

The complete app generates a three-step control Load \rightarrow intra-tile accumulate \rightarrow full accumulate



```
Reduce(accum)(tileSize by 1 par 2){ i =>
```

- Spatial generates multi-step controllers
- Spatial manages communication with DRAM
- Spatial helps express hardware datapaths





- Spatial generates multi-step controllers
- Spatial manages communication with DRAM
- Spatial helps express hardware datapaths
- Spatial makes it easy to tile





- Spatial generates multi-step controllers
- Spatial manages communication with DRAM
- Spatial helps express hardware datapaths
- Spatial makes it easy to tile and stream
- Spatial lets the user manage scheduling
 - With annotation, steps (stages) execute in pipelined fashion. "Buffering" of memories is inferred



Spatial Question

Spatial programmer's responsibility

Spatial compiler's responsibility
TensorFlow to FPGA



Recap: Why was Flash Attention powerful?



Recap: Why was FlashAttention Powerful?



Streaming execution model: Free Fusion!

Kernel-based Execution Model:

- FlashAttention prevents the materialization of the N x N matrix
- However, it requires modifying the algorithm and extra computation

• Streaming execution model:

- Avoids materialization of the N x N matrix
- Without algorithmic changes & extra computation

Preliminary: Softmax

Softmax is actually a 3-step operation



Preliminary: Softmax

Softmax is actually a 3-step operation



Attention





















Kernel-based Execution Model (Overview)





With the streaming execution model, we get fusion for free which means:

- Avoid materializing the N x N matrix ⇒ ↓ Memory Footprint
- Avoid reading & writing the intermediate N x N matrices ⇒ ↓ Memory bandwidth

An example program in a streaming execution model

Computation: Exponential & Rowsum



<pre>val sDRAM = DRAM[T](N, N) setMem(sDRAM, sVals) val outDRAM = DRAM[T](N) Accel { On-chi </pre>	-chip memory for Input & output p memory for Input & output
val S = SRAM[T](N, N)	// Input
val fifo1 = FIFO[T](2)	// Intermediate FIFOs
val fifoOUT = FIFO[T](N)	// Output
S load sDRAM	// Load the input
<pre>Stream { // Compute S'=exp(S) Foreach(0 until N, 0 until N) { (i, j) => val input = S(i, j) // Read the input val output = exp(input) // Do the computation (exp) fifo1.enq(output) // Enqueue the output } </pre>	
<pre>// Compute Rowsum(S') Foreach(0 until N) { i => val accum = Reg[T] Reduce(accum)(0 until N)</pre>	<pre>{ j => // Dequeue the input // Accumulate row-wise // Enqueue the output</pre>
outDRAM1 store fifoOUT }	// Store the output

An example program in a streaming execution model

Computation: Exponential & Rowsum



Doing the computation piece-wise -

<pre>val sDRAM = DRAM[T](N, N)</pre>	
<pre>setMem(sDRAM, sVals)</pre>	
val outDRAM = DRAM[T](N)	
Accel {	
val $S = SRAM[T](N, N)$	// Input
val fifo1 = $EIEO[T](2)$	// Intermediate EIEOs
val fifout = FIFO[T](N)	// Output
load inn	ut to the on-chin memory
S IOAC SDRAM	// Load the input
Stream {	
<pre>// Compute S'=exp(S)</pre>	
Foreach(0 until N, 0 until	N) { (i, j) =>
val input = S(i, j)	// Read the input
<pre>val output = exp(input)</pre>	<pre>// Do the computation (exp)</pre>
fifo1.enq(output)	// Enqueue the output
}	
// Compute Rowsum(S')	
$Eoreach(0 until N) \{ i = \}$	
val accum = Reg[T]	
Reduce(accum)(Q until N)	ſ ÷ _>
fife1 dea()	() -/
+itol.ded()	// Dequeue the input
	// Accumulate row-wise
fitoOUT.enq(accum.value)	// Enqueue the output
}	
outDRAM1 store fifoOUT	// Store the output
}	

An example program in a streaming execution model

Computation: Exponential & Rowsum



Doing the computation piece-wise 🧹

<pre>val sDRAM = DRAM[T](N, N)</pre>	
<pre>setMem(sDRAM, sVals)</pre>	
<pre>val outDRAM = DRAM[T](N)</pre>	
Accel {	Intermediate FIFOs
val S = SRAM[T](N, N)	// Input
val fifo1 = FIFO[T](2)	<pre>// Intermediate FIFOs</pre>
val fifoOUT = FIFO[T](N)	// Output
S load sDRAM	// Load the input
Stream {	
// Compute S'=exp(S)	
_ Foreach(0 until N, 0 u	ntil N) { (i, j) =>
val input = S(i, j)	// Read the input
val output = exp(inp	ut) // Do the computation (exp)
fifo1.eng(output)	
	Enqueue the output
	· · ·
// Compute Rowsum(S')	
Foreach(0 until N) { i	=>
val accum = Reg[T]	
Reduce(accum)(0 unti	1 N) { i =>
fifo1.deg()	Dequeue the output
$\{ \} \{ + \}$	Dequeue the output
fifoOUT.eng(accum.va	lue) // Engueue the output
}	
}	
outDRAM1 store fifoOUT	// Store the output
3	
3	

Streaming Execution Model Summary

Example using a streaming execution model

Computation: Exponential & Rowsum



Kernel-based Execution Model (Overview)





Streaming Execution Model (Overview)













































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Can we do better with FlashAttention?

- Yes!
- By paying a bit more computation cost as Flash Attention does, we can eliminate the FIFO in the middle



Can we do better with FlashAttention?

- We needed this sequence-length (N) sized FIFO to buffer the output of S' = Exp(S).
- This is because in softmax, we have to wait until the row-wise reduction (row sum) is calculated to divide the output of S' = Exp(S) with the row sum.
- Flash Attention breaks this dependency by:
 - Reordering operations
 - Using a running sum & rescaling instead of the naïve reduction (row sum)



Kernel versus Stream Execution

- More parallelism
 - FlashAttention with kernel-based execution model:
 - Cannot overlap the computation for different output tiles
 - Streaming execution model
 - Spatially maps each computation with pipeline communication
 - Can overlap (pipeline) the computation for different output tiles!
- Don't have to manually create fused kernels
 - FlashAttention with kernel-based execution model:
 - Have to manually write fused kernels in CUDA
 - Often challenging to fuse deeply due to the limit in (# of registers / SM)
 - Streaming execution model
 - Operations gets fused automatically if we write the program using FIFOs
 - Compiler can automatically generate fused executioin

Accelerator Design Summary

- Significant energy efficiency improvements from specialized accelerators (100x–1000x)
- Designing an accelerator is a tradeoff between performance and resource utilization
 - Parallelism
 - Locality
- It requires the programmer to have insight into the application
 - Where is the bottleneck
 - Is the implementation compute or memory-bound
- Spatial helps you understand the trade-off between performance and resource utilization
 - Allows rapid exploration of your algorithm
 - Enables high-level accelerator design
Reducing energy consumption idea 1: use specialized processing

(use the right processor for the job)

Reducing energy consumption idea 2: move less data

Data movement has high energy cost

- Rule of thumb in mobile system design: always seek to reduce amount of data transferred from memory
 - Earlier in class we discussed minimizing communication to reduce stalls (poor performance). Now, we wish to reduce communication to reduce energy consumption
- "Ballpark" numbers [Sources: Bill Dally (NVIDIA), Tom Olson (ARM)]
 - Integer op: ~ 1 pJ*
 - Floating point op: ~20 pJ*
 - Reading 64 bits from small local SRAM (1mm away on chip): ~ 26 pJ
 - Reading 64 bits from low power mobile DRAM (LPDDR): ~1200 pJ
- Implications
 - Reading 10 GB/sec from memory: ~1.6 watts
 - Entire power budget for mobile GPU: ~1 watt (remember phone is also running CPU, display, radios, etc.)
 - iPhone 6 battery: ~7 watt-hours (note: my Macbook Pro laptop: 99 watt-hour battery)
 - Exploiting locality matters!!!

* Cost to just perform the logical operation, not counting overhead of instruction decode, load data from registers, etc.

Suggests that recomputing values, rather than storing and reloading them, is a better answer when optimizing code for energy efficiency!

Moving data is costly!

Data movement limits performance

Many processing elements...

- = higher overall rate of memory requests
- = need for more memory bandwidth

(result: bandwidth-limited execution)

Data movement has high energy cost

- \sim 0.9 pJ for a 32-bit floating-point math op *
- ~ 5 pJ for a local SRAM (on chip) data access
- $\sim 640~\text{pJ}$ to load 32 bits from LPDDR memory









* Source: [Han, ICLR 2016], 45 nm CMOS assumption

Accessing DRAM

(a basic tutorial on how DRAM works)





DRAM array 1 transistor + capacitor per "bit"

(Recall: a capacitor stores charge)



Estimated latencies are in units of memory clocks: DDR3-1600 (Kayvon's laptop)



Load next byte from (already active) row

Lower latency operation: can skip precharge and row activation steps



DRAM access latency is not fixed

- Best case latency: read from active row
 - Column access time (CAS)

Worst case latency: bit lines not ready, read from new row

Precharge (PRE) + row activate (RAS) + column access (CAS)

Precharge readies bit lines and writes row buffer contents back into DRAM array (read was destructive)

- Question 1: when to execute precharge?
 - After each column access?
 - Only when new row is accessed?
- Question 2: how to handle latency of DRAM access?

Problem: low pin utilization due to latency of access



DRAM burst mode



DRAM chip consists of multiple banks

- All banks share same pins (only one transfer at a time)
- Banks allow for pipelining of memory requests
 - Precharge/activate rows/send column address to one bank while transferring data from another
 - Achieves high data pin utilization



Organize multiple chips into a DIMM

Example: Eight DRAM chips (64-bit memory bus)

Note: DIMM appears as a single, higher capacity, wider interface DRAM module to the memory controller. Higher aggregate bandwidth, but minimum transfer granularity is now 64 bits.



Reading one 64-byte (512 bit) cache line (the wrong way) Assume: consecutive physical addresses mapped to same row of same chip

Memory controller converts physical address to DRAM bank, row, column



Reading one 64-byte (512 bit) cache line (the wrong way)

All data for cache line serviced by the same chip Bytes sent consecutively over same pins



Reading one 64-byte (512 bit) cache line (the wrong way)

All data for cache line serviced by the same chip Bytes sent consecutively over same pins



Reading one 64-byte (512 bit) cache line

Memory controller converts physical address to DRAM bank, row, column Here: physical addresses are <u>interleaved</u> across DRAM chips at byte granularity



Reading one 64-byte (512 bit) cache line

DRAM controller requests data from new column * DRAM chips transmit next 64 bits in parallel



* Recall modern DRAM's support burst mode transfer of multiple consecutive columns, which would be used here

Memory controller is a memory request scheduler

- Receives load/store requests from LLC
- Conflicting scheduling goals
 - Maximize throughput, minimize latency, minimize energy consumption
 - Common scheduling policy: FR-FCFS (first-ready, first-come-first-serve)
 - Service requests to currently open row first (maximize row locality)
 - Service requests to other rows in FIFO order
 - Controller may coalesce multiple small requests into large contiguous requests (to take advantage of DRAM "burst modes")



Dual-channel memory system

- Increase throughput by adding memory channels (effectively widen bus)
- Below: each channel can issue independent commands
 - Different row/column is read in each channel
 - Simpler setup: use single controller to drive same command to multiple channels



Example: DDR4 memory

Processor: Intel[®] Core[™] i7-7700K Processor (in Myth cluster)

DDR4 2400

- 64-bit memory bus x 1.2GHz x 2 transfers per clock* = 19.2GB/s per channel
- 2 channels = 38.4 GB/sec
- ~13 nanosecond CAS

Memory system details from Intel's site:

Memory Specifications Max Memory Size (dependent on memory type) ? 64 GB Memory Types ? DDR4-2133/2400, DDR3L-1333/1600 @ 1.35V Max # of Memory Channels ? 2 ECC Memory Supported ‡ ? No

* DDR stands for "double data rate"

https://ark.intel.com/content/www/us/en/ark/products/97129/intel-core-i7-7700k-processor-8m-cache-up-to-4-50-ghz.html

DRAM summary

- DRAM access latency can depend on many low-level factors
 - Discussed today:
 - State of DRAM chip: row hit/miss? is recharge necessary?
 - Buffering/reordering of requests in memory controller
- Significant amount of complexity in a modern multi-core processor has moved into the design of memory controller
 - Responsible for scheduling ten's to hundreds of outstanding memory requests
 - Responsible for mapping physical addresses to the geometry of DRAMs
 - Area of active computer architecture research

Modern architecture challenge: improving memory performance:

Decrease distance data must move by locating memory closer to processors

(enables shorter, but wider interfaces)

Increase bandwidth, reduce power by chip stacking

Enabling technology: 3D stacking of DRAM chips

- DRAMs connected via through-silicon-vias (TSVs) that run through the chips
- TSVs provide highly parallel connection between logic layer and DRAMs
- Base layer of stack "logic layer" is memory controller, manages requests from processor
- Silicon "interposer" serves as high-handwidth interconnect hetween DRAM stack and processor



Technologies: Micron/Intel Hybrid Memory Cube (HBC) High-bandwidth memory (HBM) - 1024 bit interface to stack

Image credit: AMD

HBM Advantages

More Bandwidth High Power Efficiency Small Form Factor

	DDR4	LPDDR4(X)	GDDR6	HBM2	HBM2E (JEDEC)	HBM3 (TBD)
Data rate	3200Mbps	3200Mbps (up to 4266 Mbps)	14Gbps (up to 16Gb ps)	2.4Gbps	2.8Gbps	>3.2Gbps (TBD)
Pin count	x4/x8/x16	x16/ch (2ch per die)	x16/x32	x1024	x1024	x1024
Bandwidth	5.4GB/s	12.8(17)GB/s	56GB/s	307GB/s	358GB/s	>500GB/s
Density (per package)	4Gb/8Gb	8Gb/16Gb/2 4Gb/32Gb	8Gb/16Gb	4GB/8GB	8GB/16GB	8GB/16GB/ 24GB (TBD)

GPUs are adopting HBM technologies





NVIDIA P100 GPU (2016) 4096-bit interface: 4 HBM2 chips x 1024 bit interface per chip 720 GB/sec peak BW 4 x 4 GB = 16 GB capacity





NVIDIA H100 GPU (2022) 6144-bit interface: 6 HBM3 stacks x 1024 bit interface per stack 3.2 TB/sec peak BW 80 GB capacity

Xeon Phi (Knights Landing) MCDRAM

- 16 GB in package stacked DRAM
- Can be treated as a 16 GB last level cache
- Or as a 16 GB separate address space ("flat mode")
- Intel's claims:
 - ~ same latency at DDR4
 - ~5x bandwidth of DDR4
 - ~5x less energy cost per bit transferred



ste buffer in MCDRAM ("high bandwidth" memory malloc)
loat* foo = hbw_malloc(sizeof(float) * 1024);

Summary: the memory bottleneck is being addressed in many ways

- By the application programmer
 - Schedule computation to maximize locality (minimize required data movement)

By new hardware architectures

- Intelligent DRAM request scheduling
- Bringing data closer to processor (deep cache hierarchies, 3D stacking)
- Increase bandwidth (wider memory systems)
- Ongoing research in locating limited forms of computation "in" or near memory
- Ongoing research in hardware accelerated compression (not discussed today)

General principles

- Locate data storage near processor
- Move computation to data storage
- Data compression (trade-off extra computation for less data transfer)